## PATENT ABSTRACTS OF JAPAN

(11)Publication number:

2000-101245

(43) Date of publication of application: 07.04.2000

(51)Int.CI.

H05K 3/46 B32B 15/08 B32B 15/20 H05K 1/03

(21)Application number: 10-269460

(71)Applicant:

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(22)Date of filing:

24.09.1998

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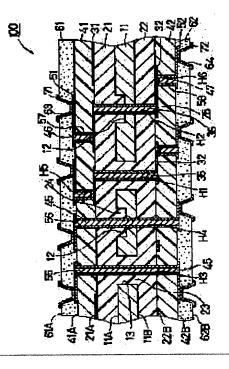
**MATSUURA TORU** 

## (54) MULTILAYER RESIN WIRING BOARD AND ITS MANUFACTURE

## (57) Abstract:

PROBLEM TO BE SOLVED: To form high-precision and fine through holes for connection by a short-time laser treatment while applying a high stiffness to a board by using a relatively thick metal plate.

SOLUTION: A multilayer resin wiring board 100 is provided with a copper plate 11 having a first major surface 11A and a second major surface 11B, plural wiring layers 31, 32, 51 and 52 positioned on either of the sides, plural insulating layers 21, 22, 41 and 42 between the copper plate 11 and the wiring layers 31, 32, 51 and 52 and between the wiring layers, a copper plate connecting via 36 which connects the wiring layers 31 and 32 sandwiching the copper plate 11 and which is formed in through holes H2 and H4 for connecting the copper plate respectively passing through the copper plate 11 and a copper plate connecting via 56 which connects the wiring layers 51 and 52 and the copper plate 11. The copper plate 11 is provided with a part 12 thinner than the other part. The through holes 36 and 56 for connecting the copper plate are formed by laser treatment passing through the thinner part 12.



## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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17.06.2002